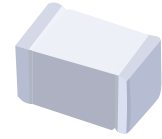
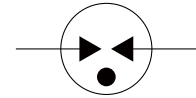


FEATURES

- | Surface Mounting Design 5.5*4.0*4.0mm
- | High Current Handling Capability 5000A @ 8/20 μs
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1



5.5*4.0*4.0mm




Schematic Symbol

APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	72-108	V
Impulse Spark-over Voltage	At 1kV/ μ s	for 99 % of measured values \leq 600	V
	At 1kV/ μ s	Typical values of distribution \leq 550	V
Impulse Discharge Current 2)	8/20 μ s	5000	A
Insulation Resistance	DC=50V	\geq 1	G Ω
Capacitance at 1MHz	V _{DC} =0.5V	\leq 0.6	pF
Operating And Storage Temperature		-40-125	$^{\circ}$ C

1) In ionized mode

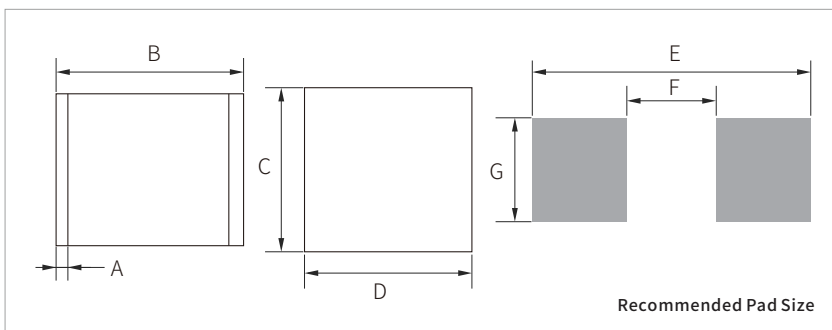
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-311

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 \pm 5 $^{\circ}$ C; Time of dip soldering: 10s, 1time

NOTE:Up-screen program can be specified by customer' s request via contacting Semiware service

DIMENSIONS AND RECOMMENDED SOLDERING PAD



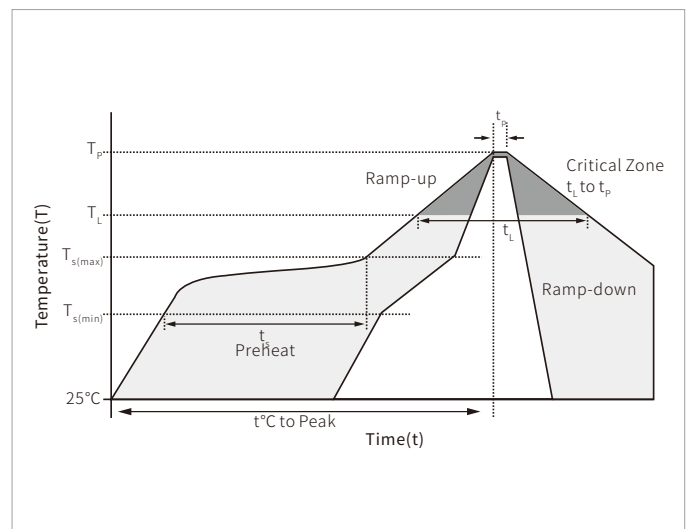
Ref.	mm
A	0.45 \pm 0.1mm
B	5.5 \pm 0.2mm
C	4.0 \pm 0.2mm
D	4.0 \pm 0.2mm
E	6.10mm
F	4.40mm
G	4.20mm

SOLDERABILITY TEST

Solderability	
Solder Pot Temperature	Solder Dwell Time
245°C ± 5°C	4-6 seconds

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak $T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time(min to max)(t_s)	60 – 150 seconds
Peak Temperature (T_p)		260 °C
Time within 5°C of actual peak Temperature (t_p)		20-40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C



ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
SG5540B090	5.5*4.0*4.0mm	800PCS	13"

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By QR Code

Website



Wechat

To find your local partner within Semiware' s global website: www.semiware.com

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